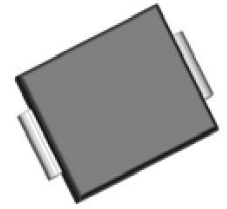


Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V
- Low profile
- Build-in strain relief, ideal for automated placement
- Glass passivated chip junction



DO-214AB (SMC)[Ⓢ]

Mechanical Data

- Case: JEDEC DO-214AB (SMC)
- Terminals: solder plated, solderable per MIL-STD-750, Method 2026
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Polarity: color band denotes cathode end

Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	SN8A	SN8B	SN8D	SN8G	SN8J	SN8K	SN8M	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at TL (See Fig.1)	I _{F(AV)}	8.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed On Rated Load	I _{FSM}	200							A
Operating Junction and Storage Temperature Range	T _J , T _{STG}	- 55 to + 150							°C

Electrical Characteristics (T_A=25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	SN8A	SN8B	SN8D	SN8G	SN8J	SN8K	SN8M	Unit
Maximum Instantaneous Forward Voltage	8A	V _F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	I _R	5							μA
	T _A =100°C		50							
Typical Thermal Resistance1)	Junction to Ambient	R _{θJA}	28							°C/W
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	50							pF

Note:1) The thermal resistance from junction to ambient, case or lead, mounted on P.C.B with 30×30mm copper pads

Ratings and Characteristic Curves

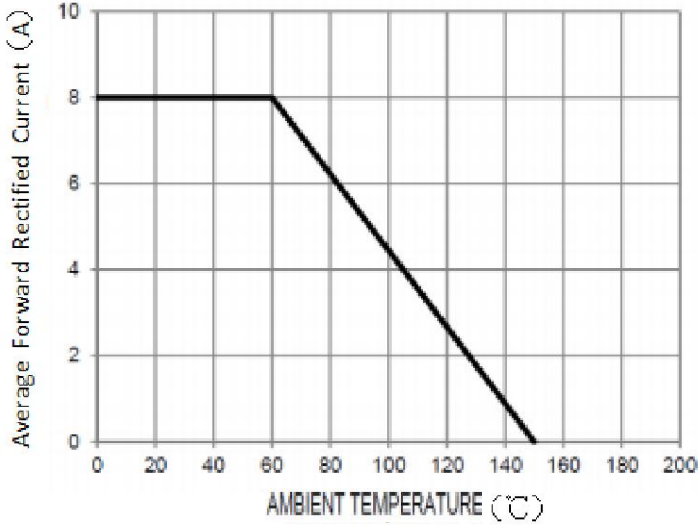


Figure 1. Forward Current Derating Curve

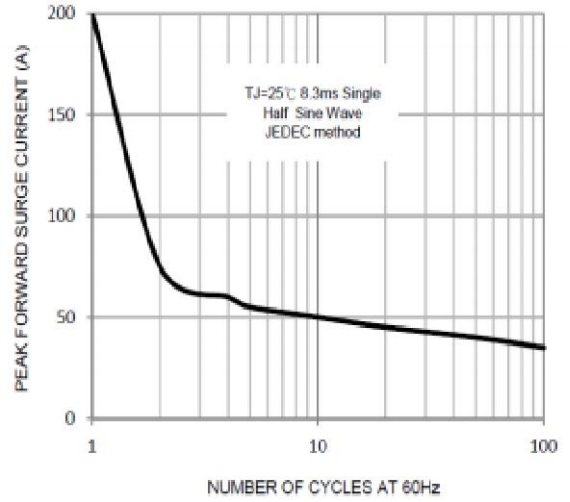


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

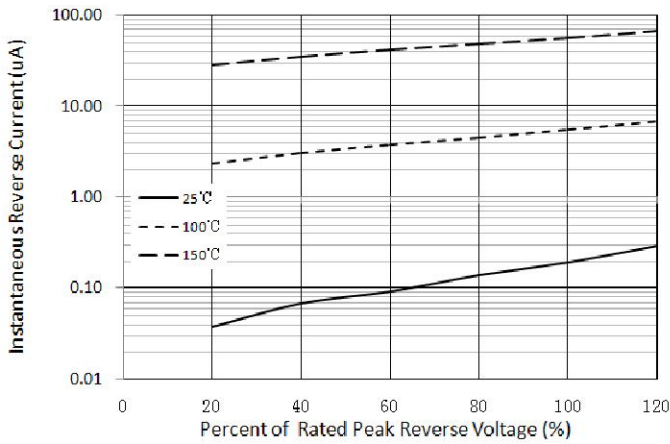


Figure 3. Typical Reverse Characteristics

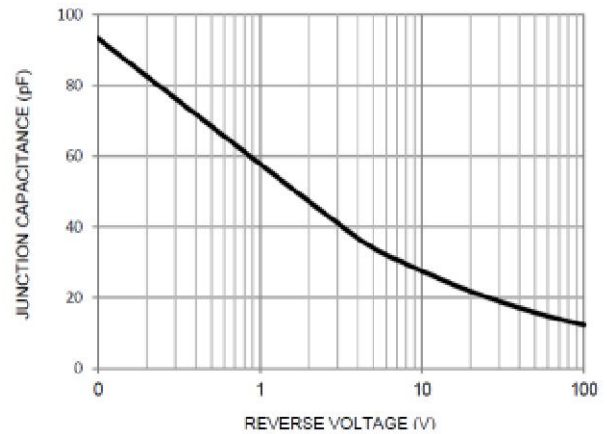


Figure 4. Typical Junction Capacitance

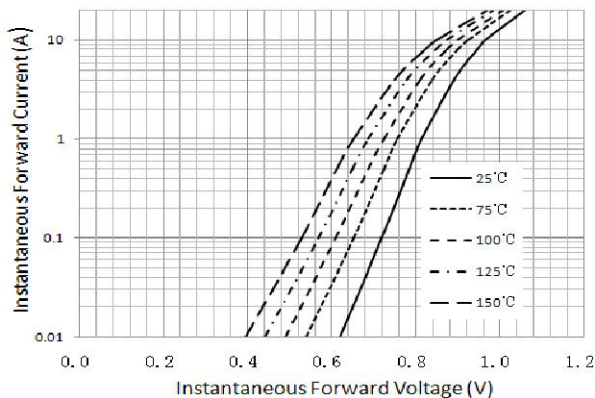


Figure 5. Typical Instantaneous Forward Characteristics

Package Outline Dimensions

